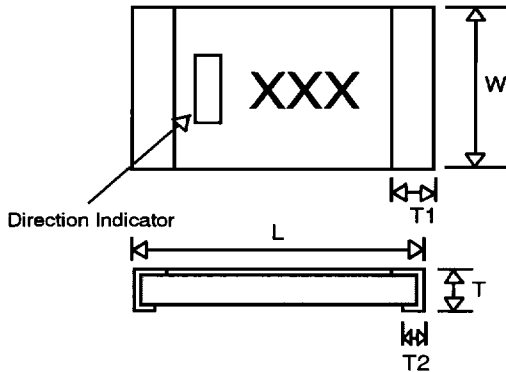


THIN FILM CHIP INDUCTOR

- Excellent High Frequency Applications
- Suitable for Reflow & Wave Soldering
- Low Tolerance $\pm 2\%$ available
- Small size allows for High Density Mounting (0805, 1206)
- Yellow Three-Figure Marking on Blue Protective Coating

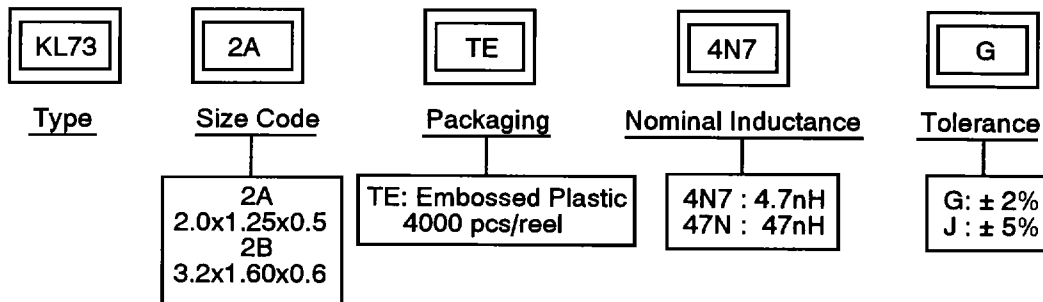
DIMENSIONS



DIMENSIONS	L	W	T	T1	T2
2A (mm) (in)	2.0 ^{+0.2} 0.08 ^{+0.008}	1.25 ^{+0.2} 0.05 ^{+0.008}	0.5 ^{+0.1} 0.02 ^{+0.004}	0.4 ^{+0.2} 0.015 ^{+0.008}	0.3 ^{+0.2-0.1} 0.012 ^{+0.008-0.004}
2B (mm) (in)	3.2 ^{+0.2} 0.125 ^{+0.008}	1.6 ^{+0.2} 0.063 ^{+0.008}	0.6 ^{+0.1} 0.024 ^{+0.004}	0.5 ^{+0.2} 0.02 ^{+0.008}	0.4 ^{+0.2-0.1} 0.015 ^{+0.008-0.004}

PART MARKING	VALUE(nH) 2.2 - 8.2	VALUE(nH) 10 - 47
2A	Ex. = 2.2 = 2.2nH	Ex. = 15 = 15 nH
2B	Ex. = 2N2 = 2.2nH	Ex. = 15N = 15nH

ORDERING & SPECIFYING INFORMATION



STANDARD APPLICATIONS

TYPE	Ind. (nH)	Inductance Tolerance (%)	Quality Factor (min)	SRF Mhz min	DC. Res Ω max	Allowable Current mA max.	Meas. Freq. Mhz			
KL732A2N2	2.2	± 2% ± 5%	28	3000		500	500			
KL732A2N7	2.7									
KL732A3N3	3.3									
KL732A3N9	3.9		29							
KL732A4N7	4.7									
KL732A5N6	5.6		30							
KL732A6N8	6.8									
KL732A8N2	8.2									
KL732A10N	10		32					2750	450	
KL732A12N	12		30					2500		
KL732A15N	15		28					2250		400
KL732B2N2	2.2	± 2% ± 5%	32	3000		500	500			
KL732B2N7	2.7		38							
KL732B3N3	3.3		40							
KL732B3N9	3.9		42							
KL732B4N7	4.7		44							
KL732B5N6	5.6									
KL732B6N8	6.8		40							
KL732B8N2	8.2									
KL722B10N	10		44					2900	450	
KL732B12N	12		42					2700		
KL732B15N	15							2400		
KL732B18N	18							2100		
KL732B22N	22							1940		400
KL732B27N	27							30	1680	350
KL732B33N	33		28					1500	300	200
KL732B39N	39							1300		
KL732B47N	47							1270		

ENVIRONMENTAL & MECHANICAL CHARACTERISTICS

PARAMETER	LIMITS	TEST METHOD
Terminal Pull Strength	No evidence of breakdown	Terminals shall withstand a pull of 0.5Kg in a Horizontal direction.
Terminal Bending Strength	No evidence of breakdown. Δ R/R ± 1%, Δ L/L ± 2% Δ Q/Q ± 20%	3 mm deflection in either direction
Resistance to Solder Heat	No evidence of outer damage Δ L/L ± 2% Δ Q/Q ± 20%	Immerse in solder (H63A) at 260 ± 5 °C for 10 ± 1.0 sec.
Solderability	95% of the terminal should be covered with new solder	Immerse in solder (H63A) at 230 ± 5 °C for 3 ± 0.5 sec.
Low Temperature Characteristics	Δ L/L ± 2% Δ Q/Q ± 20%	Store at -40 ± 3 °C, for 1000 hours.
Resistance to Heat	Δ L/L ± 2% Δ Q/Q ± 20%	Store at 125 ± 2 °C, for 1000 hours.
Thermal Shock	Δ L/L ± 2% Δ Q/Q ± 20%	-40°C for 30 min. and +125°C for 30 min., 100 Cycles.
Moisture Endurance	No evidence of damage Δ L/L ± 2% Δ Q/Q ± 20%	40 ± 2°C Temperature 90-95% Relative Humidity. 1000 Hrs
Vibration	No evidence of breakdown Δ L/L ± 2% Δ Q/Q ± 20%	Frequency 10 - 55 - 10 Hz, 1.5mm Amp. 2 hours in the X,Y and Z directions.
Dropping	No evidence of damage Δ L/L ± 2% Δ Q/Q ± 20%	MIL-STD-202F Method 213B Item 4.1 condition C
Resistance to Solvents	No outer damage Marking remains legible.	MIL-STD - 202, Method 215